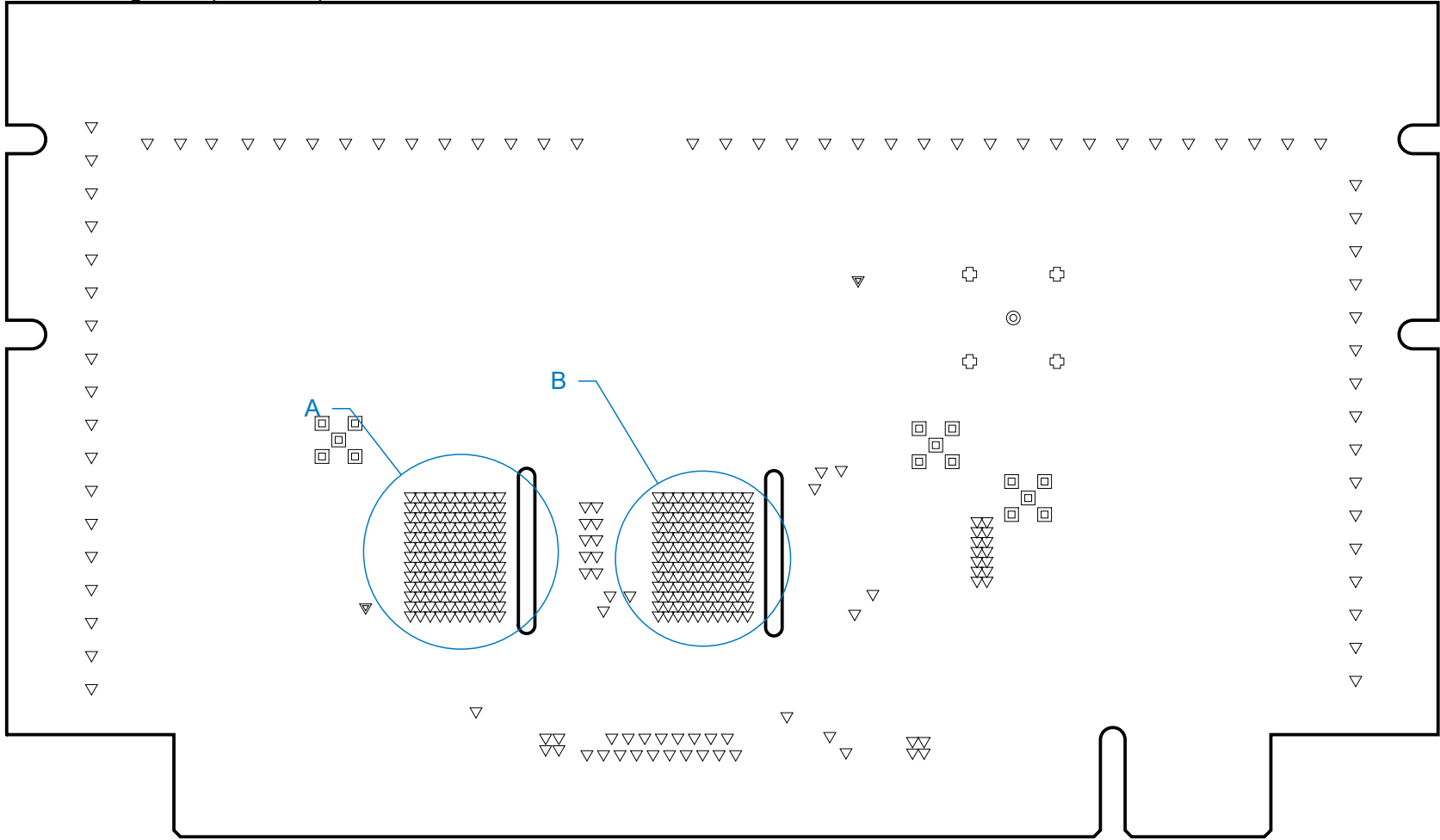
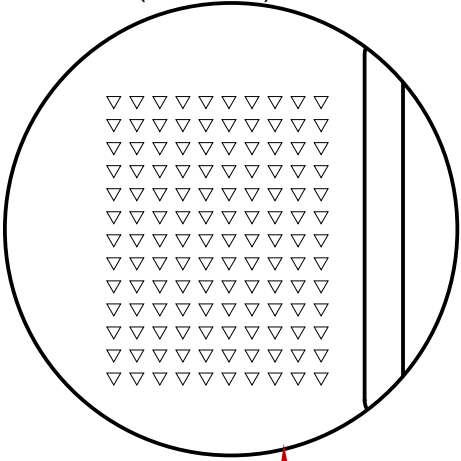


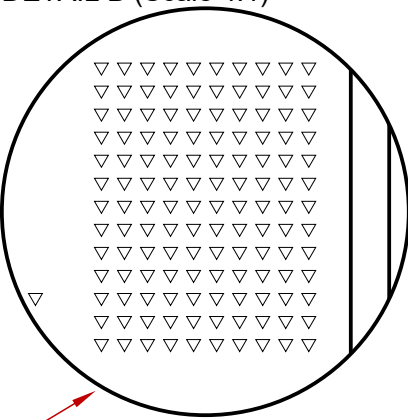
Drill Drawing View (Scale 2:1)



DETAIL A (Scale 4:1)




DETAIL B (Scale 4:1)



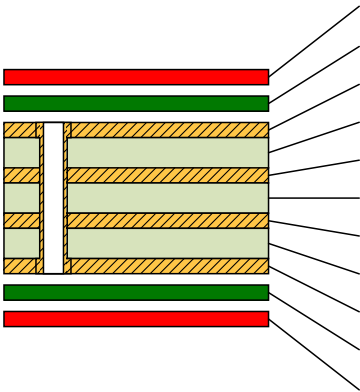
Notes:

1. Fabricate per IPC 6012 Class II
2. Material: FR4 equivalent.
Tg>=170°
3. Cu weight all layers: 4 oz.
4. Total board thickness after plating: 0.062 +/- 8%
5. Final finish: ENIG
6. Soldermask both sides using photo-imagable process. Color: green
7. Silkscreen both sides using non-conductive ink. Color : white
8. All holes to be +/- 0.003 unless otherwise specified. Hole sizes are given after plating. Plated thru-hole shall have a min of 0.002 Cu internal plating.
9. Remove all burrs and sharp edges 0.015 min.
10. Surface finish: ENIG

 Thermal vias in Deatils 'A' and 'B' are to be filled with SAN-EI PHP-900 Epoxy prior to plating. All other vias are tented.

 No gold fingers required.

Layer Stack Legend



Top Overlay			Legend	GTO
Surface Material	Top Solder	0.4mil	Solder Resist	Solder Mask
CF-006	TOP	5.5mil	Signal	GTS
Core		10.0mil	Dielectric	GTL
CF-006	INNER1	5.5mil	Signal	G1
Core		21.0mil	Dielectric	G2
CF-006	INNER2	5.5mil	Signal	G2
Core		10.0mil	Dielectric	GBL
CF-006	BOTTOM	5.5mil	Signal	GBS
Surface Material	Bottom Solder	0.4mil	Solder Resist	Solder Mask
	Bottom Overlay		Legend	GBO

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
▽	390	12.0mil	Plated	
□	15	33.1mil	Plated	
◎	1	45.0mil	Plated	
⊕	4	70.0mil	Plated	
▽	2	125.0mil	Non-Plated	
412 Total				



Title: TOLL-pkg MOSFET Mod. Accessory Board

Drawing No: TOLL_HB_Rev1

Date: Aug. 28, 2023 Size: B Revision: 3.0 Sheet: 1 of 3

1

1

2

2

3

3

4

4

